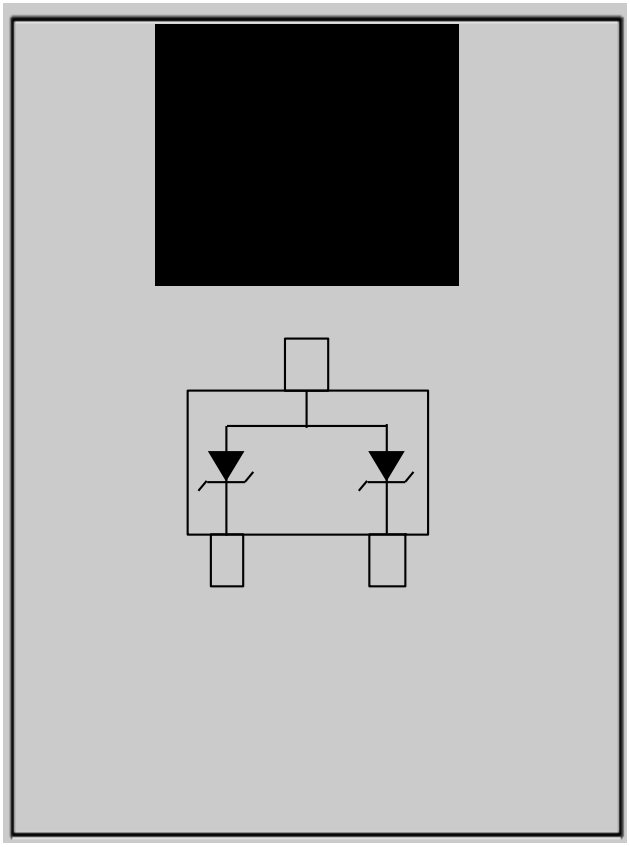


- Transient protection for each line according to IEC61000-4-2(ESD): ±30kV contact, ±30kV air IEC61000-4-5: 30A (tp=8/20μs)
- Low leakage current
- Ultra low clamping voltage
- RoHS Compliant

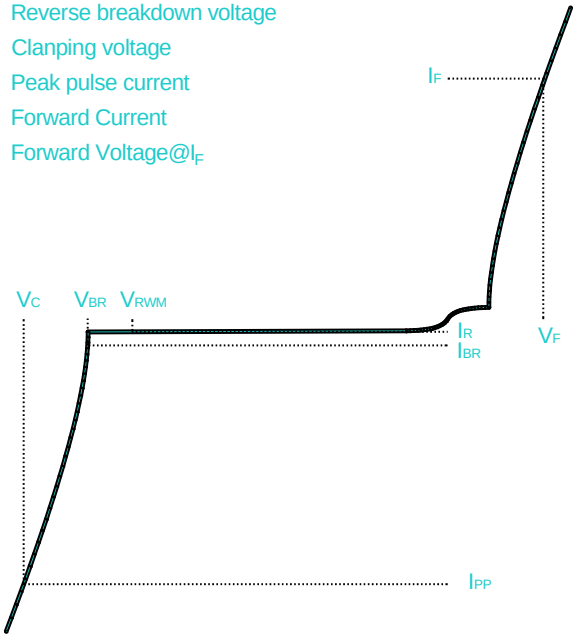
- Peripherals
- Industrial Equipment
- Notebook Computers
- Portable Instrumentation
- Microprocessor Based Equipment
- Cell Phone Handsets and Accessories
- Personal Digital Assistants (PDAs) and Pagers

- Package: SOT-23

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V_{RWM}	Reverse stand-off voltage
I_R	Reverse leakage current
V_{BR}	Reverse breakdown voltage
V_C	Clanping voltage
I_{PP}	Peak pulse current
I_F	Forward Current
V_F	Forward Voltage@I_F



■

Peak pulse power (t_p = 8/20μs)	P_{pk}	510	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	30	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	T_J	-55~150	℃
Storage temperature	T_{STG}	-55~150	℃

Notes:

CAUTION: Stresses above those listed in “Absolute Maximum Ratings” may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

■

Reverse Standoff Voltage	V_{RWM}	V				8
Reverse leakage current	I_R	μA	V_{RWM} = 8V			10
Reverse breakdown voltage	V_{BR}	V	I_T = 1mA	8.5		
Forward Voltage	V_F	V	I_F=10mA			1.25
Clamping voltage [1)]	V_C	V	I_{PP} = 1A, t_p = 8/20μs		9.8	10
			I_{PP} = 30A, t_p = 8/20μs		15	17
Junction capacitance	C_J	pF	V_R = 0V, f = 1MHz		200	

Notes:

(1). Non-repetitive current pulse, according to IEC61000-4-5.

(2). TLP parameter: Z_0 = 50Ω, t_p = 100ns, t_r = 2ns, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

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ESD0812E	F2	Approximate 10	3000	30000	120000	7 reel

Fig.1 8/20us Waveform Per iec6100-4-5

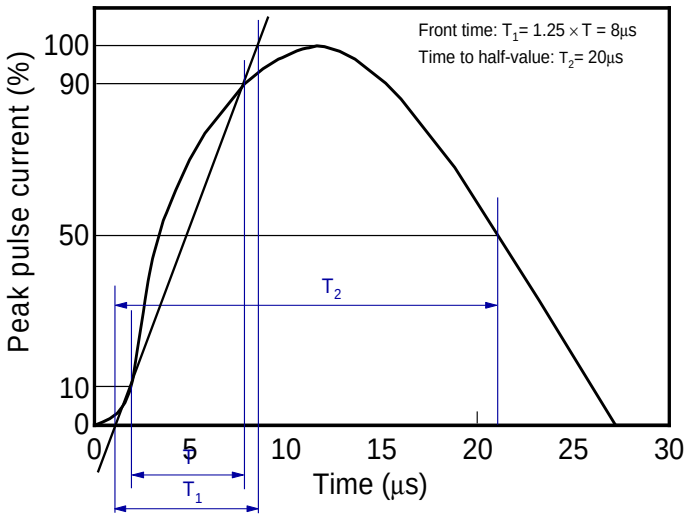


Fig.2 Contact Discharge Current Waveform per IEC61000-4-2

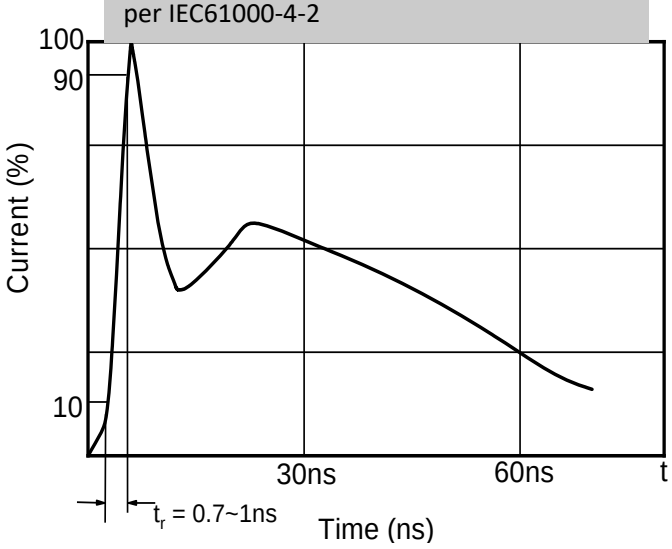
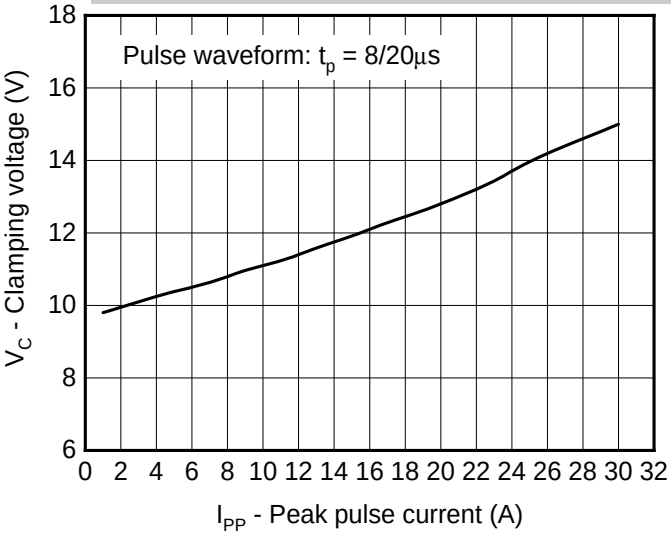
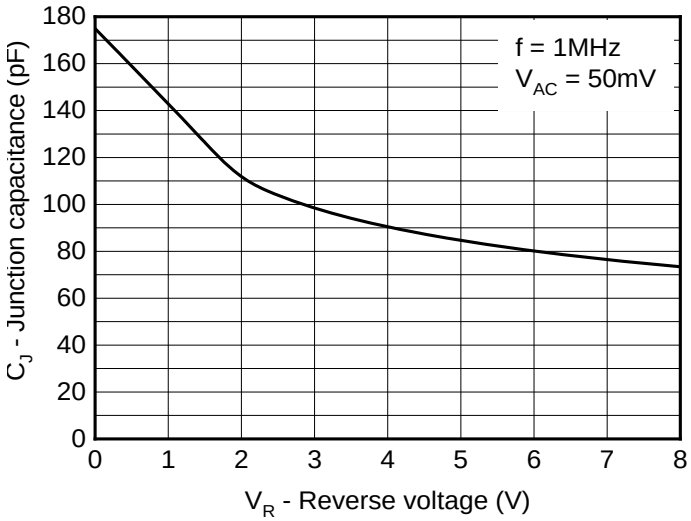
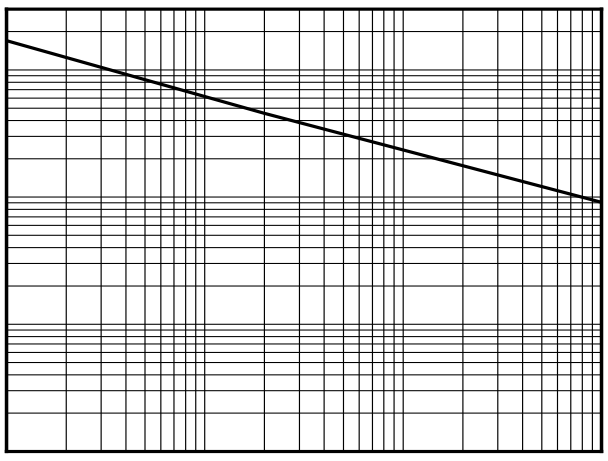


Fig.3 ClampingVoltage VS Peak Pulse Current





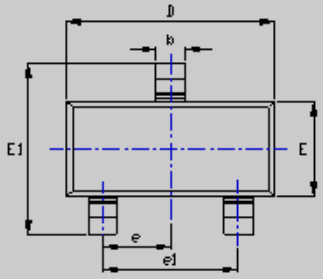


μ

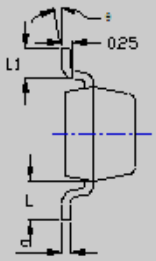
Fig.6 Power Derating Curve



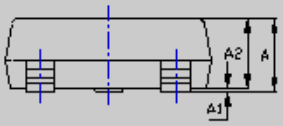
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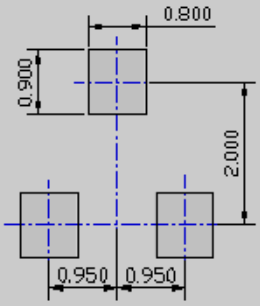
TOP VIEW



SIDE VIEW



SIDE VIEW



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
θ	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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